

METHODS FOR MAKING REINFORCED WAFER POLISHING PADS AND APPARATUSES IMPLEMENTING THE SAME

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ABSTRACT OF THE DISCLOSURE

As one of many embodiments of the present invention, a seamless polishing apparatus for utilization in chemical mechanical polishing is provided. The seamless

10 polishing apparatus includes a polishing pad where the polishing pad is shaped like a belt and has no seams. The seamless polishing apparatus also includes a base belt where the base belt includes a reinforcement layer and a cushioning layer. In addition, the cushioning layer is an intermediary layer between the polishing belt pad and the base belt.

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